

**AMENDMENTS TO THE CLAIMS, COMPLETE LISTING OF CLAIMS
IN ASCENDING ORDER WITH STATUS INDICATOR**

Please amend the following claims as indicated.

1. (Currently Amended) A scribe method for a brittle material substrate, in which forming a plurality of scribe lines are formed in directions intersecting with one another in a surface of the a brittle material substrate, said method comprising

forming at least one scribe line in a first direction by a scribe means to generate a high-penetration vertical crack in the first direction in the brittle material substrate,

forming at least one scribe line in a second direction by a scribe means to generate a high-penetration vertical crack in the second direction in the brittle material substrate,

wherein at least one scribe line in the second direction intersects with at least one scribe line of the first direction,

wherein the formation of the intersection between the scribe line in the second direction and the scribe line of the first direction occurs without the scribe means being pressed against the existing scribe line in the brittle material substrate

wherein, after forming at least one scribe line in a first direction by a scribe means generating a high-penetration vertical crack in the brittle material substrate by applying impacts of a short period to the point on the surface of the brittle material substrate, at least one scribe line of a second direction along a direction intersecting with the at least one scribe line of the first direction is formed with the scribe means by scribing without producing intersections with the scribe line(s) of the first direction.

2. (Currently Amended) A scribe apparatus for carrying out the scribe method according to claim 1, the scribe apparatus comprising:

a scribe means for generating a high-penetration vertical crack in the brittle material substrate by applying impacts of a short period to the point on the surface of the brittle material substrate, and

a travel motion control means for letting the scribe means travel while avoiding scribe lines formed in the first direction when forming the at least one scribe line of the second direction with the scribe means controlling the travel motion of said scribe means, wherein said travel motion control means prevents said scribe means from traveling across the point of intersection between said scribe lines of the first and second directions.

3. (Withdrawn) A scribe method for a brittle material substrate, in which a plurality of scribe lines intersecting with one another are formed in a surface of the brittle material substrate, wherein, when sequentially forming in the surface of the brittle material substrate at least one scribe line of a first direction and at least one scribe line of a second direction intersecting with the at least one scribe line of the first direction with a scribe means generating a high-penetration vertical crack in the brittle material substrate by applying impacts of a short period to the point on the surface of the brittle material substrate, the relation between a load P1 that is applied to the scribe means while forming the at least one scribe line in the first direction and a load P2 that is applied to the scribe means while forming the at least one scribe line in the second direction is set to $P1 > P2$.

4. (Withdrawn) A scribe apparatus for carrying out the scribe method according to claim 3, the scribe apparatus comprising:

a scribe means generating a high-penetration vertical crack in the brittle material substrate by applying impacts of a short period to the point on the surface of the brittle material substrate; and

a load control means for controlling a load applied to the scribe means such that the relation between the load P1 that is applied to the scribe means while forming the at least one scribe line in the first direction and the load P2 that is applied to the scribe means while forming the at least one scribe line in the second direction is $P1 > P2$.

5. (New) The scribe method according to claim 1, wherein the scribe means generates the high-penetration vertical crack by applying impacts of a short period to the point on the surface of the brittle material substrate.

6. (New) The scribe method according to claim 5, wherein the scribe means comprises a cutter having a plurality of protrusions formed by a plurality of grooves.

7. (New) The scribe method according to claim 6, wherein the grooves comprise a shape selected from the group consisting of U-shape, V-shape, sawtooth shape, and rectangular shape.

8. (New) The scribe method according to claim 1, wherein the scribe means presses against the brittle material substrate at a scribe start position or a scribe end position at a location which is within an advance distance of the vertical crack and which is distant from the existing scribe line.

9. (New) The scribe method according to claim 1, wherein the scribe means does not press against the existing scribe line in the brittle material substrate in a vicinity around the existing scribe line.

10. (New) The scribe method according to claim 9, wherein the vicinity around the existing scribe line comprises a distance of 0.5 to 0.7 mm on either side of the existing scribe line.

11. (New) The scribe apparatus according to claim 2, wherein the scribe means comprises a cutter having a plurality of protrusions formed by a plurality of grooves.

12. (New) The scribe apparatus according to claim 11, wherein the grooves comprise a shape selected from the group consisting of U-shape, V-shape, sawtooth shape, and rectangular shape.

13. (New) The scribe apparatus according to claim 2, wherein the scribe means presses against the brittle material substrate at a scribe start position or a scribe end position at a location which is within an advance distance of the vertical crack and which is distant from the existing scribe line.

14. (New) The scribe apparatus according to claim 2, wherein the scribe means does not press against the existing scribe line in the brittle material substrate in a vicinity around the existing scribe line.

15. (New) The scribe apparatus according to claim 14, wherein the vicinity around the existing scribe line comprises a distance of 0.5 to 0.7 mm on either side of the existing scribe line.